

SOT462-2

plastic rectangular-DIL-bent-SIL (reverse bent) power package; 13 leads, 1.7 mm pitch, 23.7 mm x 12 mm x 4.5 mm body

11 October 2018

Package information

1 Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	RDBS13P
Package type industry code	RDBS13P
Package style descriptive code	RDBS (right-angle DIL-bent-SIL)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	12-03-2003
Manufacturer package code	SOT462

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	23.4	23.7	24	mm
package width	11.8	12	12.2	mm
package height	4.4	4.5	4.6	mm
nominal pitch	-	1.7	-	mm
actual quantity of termination	-	13	-	



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2 Package outline

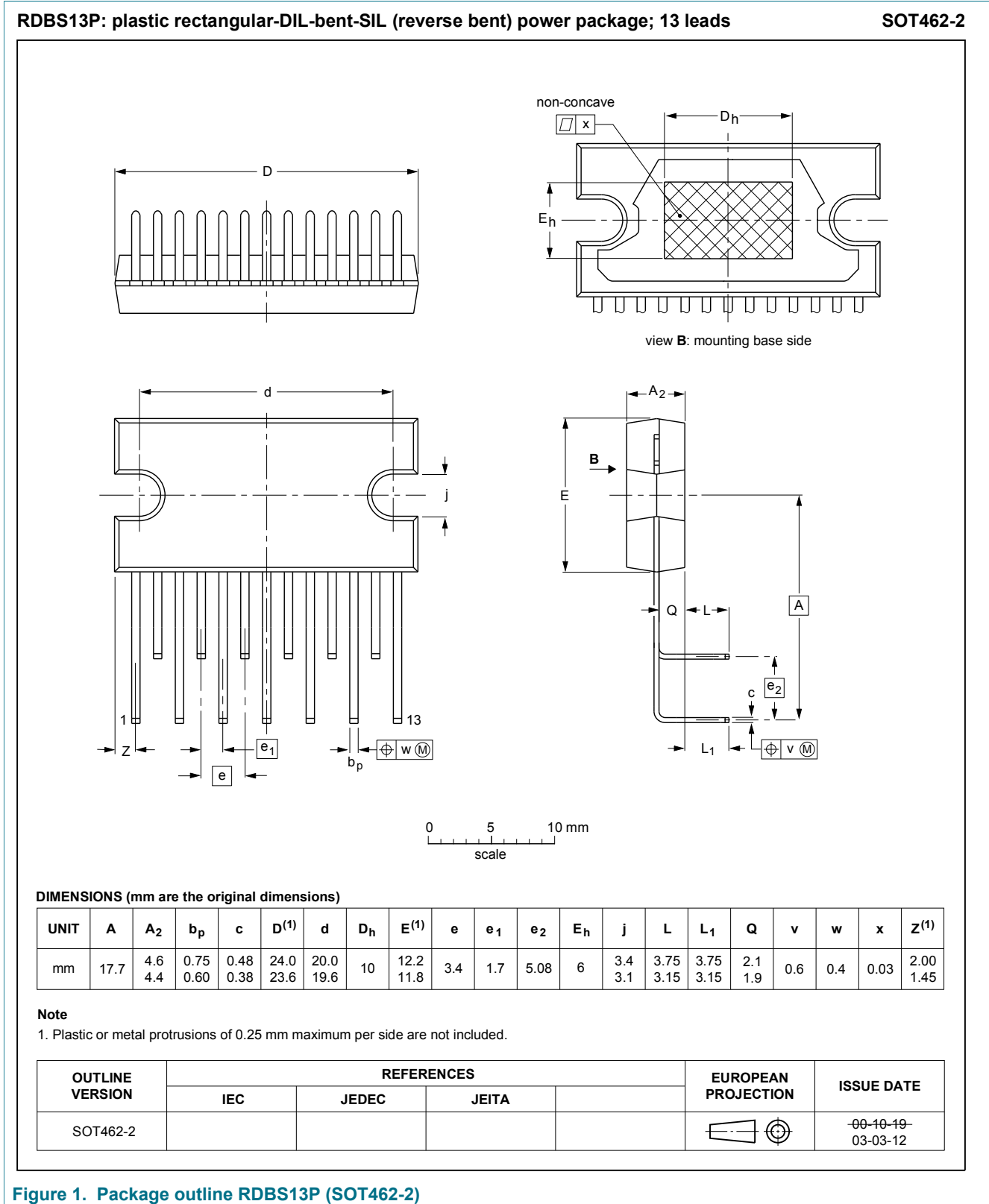


Figure 1. Package outline RDBS13P (SOT462-2)

3 Legal information

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